



# MJ P-Channel Enhancement Mode Power MOSFET

## Description

The MJ60P65K uses advanced trench technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This device is well suited for high current load applications.

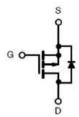
#### General Features

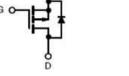
# ◆ V<sub>DS</sub> =-60V.I<sub>D</sub> =-65A $R_{DS(ON)}$ <18m $\Omega$ @ Vgs=-10V

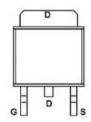
# Application

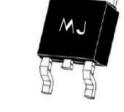
◆ Load switch

- ♦ High density cell design for ultra low Rdson
- ◆ Fully characterized avalanche voltage and current
- ◆ Good stability and uniformity with high Eas
- Excellent package for good heat dissipation









Schematic diagram

Marking and pin assignment

TO-252-2L top view

## 100% UIS TESTED! 100% ΔVds TESTED!

# Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ60P65K	MJ60P65K	TO-252-2L	ii ii	-	2

## Absolute Maximum Ratings (Tc =25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	-60	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	ID	-65	А
Drain Current-Continuous(Tc =100°C)	ID(100°C)	-42.3	А
Pulsed Drain Current	Ідм	-260	А
Maximum Power Dissipation	Po	130	W
Derating factor		0.87	W/°C
Single pulse avalanche energy (Note 5)	Eas	722	mJ
Operating Junction and Storage Temperature Range	Тл,Тѕтс	-55 To 175	°C

#### Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	Rejc	1.15	°C/W
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# Electrical Characteristics (Tc =25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	'					
Drain-Source Breakdown Voltage	BVDSS	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-60	-	-	V
Zero Gate Voltage Drain Current	loss	V <sub>DS</sub> =-60V,V <sub>GS</sub> =0V	-	-	-1	μΑ
Gate-Body Leakage Current	lgss	V <sub>DS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	VGS(th)	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =-250μA	-2.0	-2.6	-3.5	V
Drain-Source On-State Resistance	Rds(on)	V <sub>GS</sub> =-10V, I <sub>D</sub> =-20A	-	13	18	mΩ
Forward Transconductance	grs	V <sub>DS</sub> =-5V,I <sub>D</sub> =-20A	-	25	-	S
Dynamic Characteristics (Note 4)	-					
Input Capacitance	Clss		-	5814	-	PF
Output Capacitance	Coss	V <sub>DS</sub> =-25V,V <sub>GS</sub> =0V F=1.0MHz	-	483	-	PF
Reverse Transfer Capacitance	Crss	-	-	234	-	PF
Switching Characteristics (Note 4)	'					
Turn-on Delay Time	t <sub>d(on)</sub>		-	18	-	nS
Turn-on Rise Time	tr	VDD=-30V, RL=1.5Ω	-	20	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	V <sub>GS</sub> =-10V,R <sub>G</sub> =3Ω	-	55	-	nS
Turn-Off Fall Time	tf		_	35	-	nS
Total Gate Charge	Qg		-	75	-	nC
Gate-Source Charge	Qgs	V <sub>DS</sub> =-30V,I <sub>D</sub> =-20A V <sub>GS</sub> =-10V	_	16	_	nC
Gate-Drain Charge	Qgd	-	-	19	-	nC
Drain-Source Diode Characteristics	l l					
Diode Forward Voltage (Note 3)	VsD	V <sub>GS</sub> =0V,I <sub>S</sub> =-20A	-	-	-1.2	V
Diode Forward Current (Note 2)	ls		-	-	-65	А
Reverse Recovery Time	trr	TJ=25°C, IF=-20A	_	49	_	nS
Reverse Recovery Charge	Qrr	di/dt=-100A/µs (Note 3)	_	71	-	nC
Forward Turn-On Time	ton	Intrinsic turn-on time is no	egligible(tu	ırn-on is d	ominated b	y LS+LC

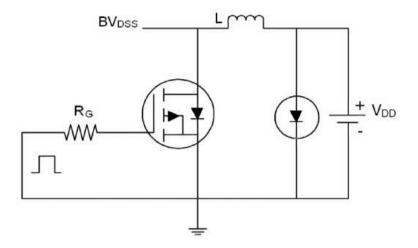
# Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t ≤ 10 sec.
- ③ Pulse Test: Pulse Width ≤ 300 $\mu$ s, Duty Cycle ≤ 2%.
- 4 Guaranteed by design, not subject to production

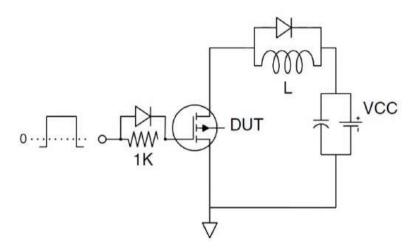




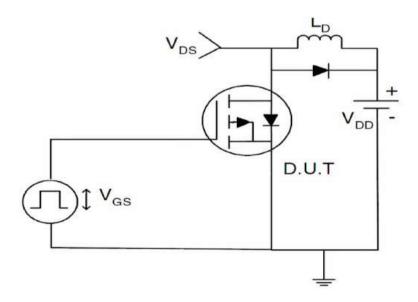
# Test circuit



Eas test Circuit



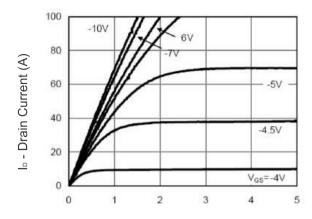
Gate charge test Circuit

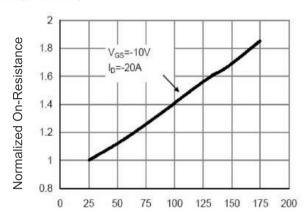


Switch Time Test Circuit



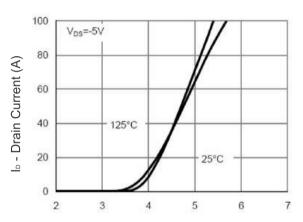
# Typical Electrical and Thermal Characteristics (Curves)



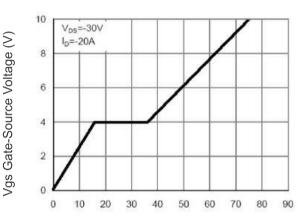


Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics

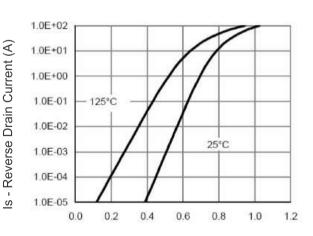


TJ -Junction Temperature(°C)
Figure 4 Rdson-Junction Temperature



Vgs Gate-Source Voltage (V)
Figure 2 Transfer Characteristics

Qg Gate Charge (nC)
Figure 5 Gate Charge

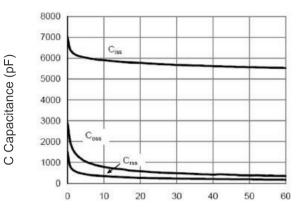


I<sub>D</sub> - Drain Current (A)
Figure 3 Rdson- Drain Current

Vsd Source-Drain Voltage (V)
Figure 6 Source- Drain Diode Forward



lo - Drain Current (A)



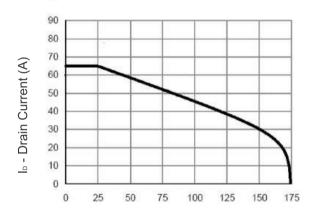
BV<sub>DSS</sub> (norm) V<sub>OS</sub>=0 I<sub>D</sub>=250μA 1.2 1.1 1.0 0.9 0.8 -50 0 50 100 T<sub>J</sub>(\*C)

Vds Drain-Source Voltage (V)

Figure 7 Capacitance vs Vds

1000.0 10us 100.0 100µs R<sub>DS(ON)</sub> 1ms 10.0 10ms DC 1.0 T<sub>J(Max)</sub>=175°C T<sub>c</sub>=25°C 0.1 0.0 0.01 0.1 1 10 100

TJ -Junction Temperature(°C)
Figure 9 BVpss vs Junction Temperature

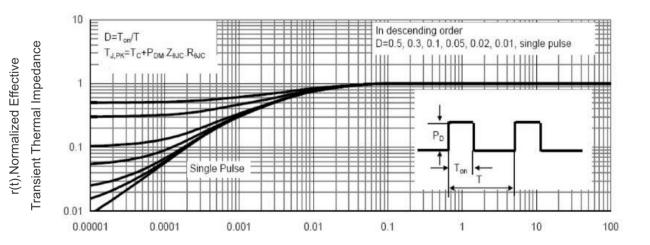


Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area

T<sub>J</sub> -Junction Temperature(°C)

Figure 10 I<sub>D</sub> Current Derating vs Junction

Temperature



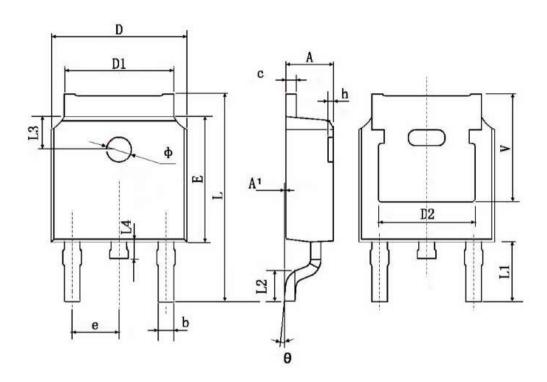
Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance



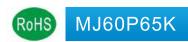


# TO-252 Package Information



Symbol	Dimensions	In Millimeters	Dimension	s In Inches
Symbol	Min.	Max.	Min.	Max.
Α	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
С	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.8	4.830 TYP.		TYP.
E	6.000	6.200	0.236	0.244
е	2.186	2,386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900	TYP.	0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600	TYP.	0.063	TYP.
L4	0.600	1.000	0.024	0.039
Ф	1.100	1.300	0.043	0.051
θ	0°	8°	0 °	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211	TYP.





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